



FEATURES

- Circular active area
- TO-39, 3 pin package
- Excellent stability after EUV exposure
- Windowless package for responsivity to 1nm

Dimensions are in inch [metric] units.

ELECTRO-OPTICAL CHARACTERISTICS AT 25°C

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Active Area			Ø2.5		mm ²
Responsivity, \mathcal{R}	See attached graph				
Shunt Resistance, R_{sh}	@ ± 10 mV	20			MOhms
Reverse Breakdown Voltage, V_R	$I_R = 1 \mu A$		20		Volts
Capacitance, C	$V_R = 0V$			1	nF
Response Time, tr	$R_L = 50 \Omega, V_R = 15V$		1	2	nsec

THERMAL PARAMETERS

STORAGE AND OPERATING TEMPERATURE RANGE	
Ambient	-10° TO 40°C
Nitrogen or Vacuum	-20°C TO 80°C
Maximum Junction Temperature	70°C
Lead Soldering Temperature ¹	260°C

¹0.08" from case for 10 seconds

